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Nicole Barrese 10-18-04
(Signature & date)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

October 15, 2004

Venigalla, et al. :

Group Art Unit: To be Assigned

Serial No. 10/711,369

Examiner: To Be Assigned

Filed: 9/14/04 :

International Business Machines Corporation
2070 Route 52
Hopewell Junction, NY 12533

TITLE: CERIA-BASED POLISH PROCESSES AND CERIA-BASED SLURRIES

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

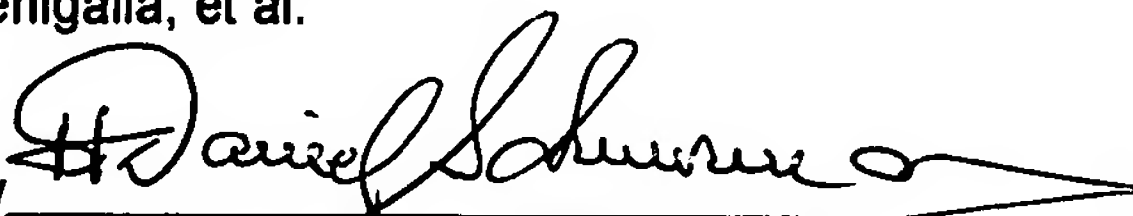
Sir:

Pursuant to the duty of disclosure set forth in 37 C.F.R. 1.56, and further pursuant to the provisions of 37 C.F.R. 1.97 and 1.98, applicants hereby respectfully submit copies of the non-US patents and publications as listed on Form PTO-1449, attached hereto.

In citing these documents, no representation is made nor intended as to the pertinency or non-pertinency of the art, that better art than that listed is not available, or that other art is not applicable.

No fee is believed to be due for this submission. If any fees are required, however, the Commissioner is hereby authorized to charge such fees to Deposit Account No. 09-0458.

Respectfully submitted,
Venigalla, et al.

By 
H. Daniel Schumann
Registration No. 35,791
Telephone No. 845-894-2481

INFORMATION DISCLOSURE CITATION

(Use several sheets if necessary)

OCT 20 2004



Docket Number (Optional)

FIS920040210US1

Application Number

10/711,369

Applicant(s)

Venigalla, et al.

Filing Date

September 14, 2004

Group Art Unit

U.S. PATENT DOCUMENTS

*EXAMINER INITIAL	REF	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE

U.S. PATENT APPLICATION PUBLICATIONS

*EXAMINER INITIAL	REF	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
		20040040217	03/04/2004	Takashina, et al.			
		20030211747	11/13/2003	Hedge, et al.			
		20030092271	05/15/2003	Jindal, et al.			
		20030047710	03/13/2003	Babu, et al.			

FOREIGN PATENT DOCUMENTS

	REF	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
							YES	NO

OTHER DOCUMENTS

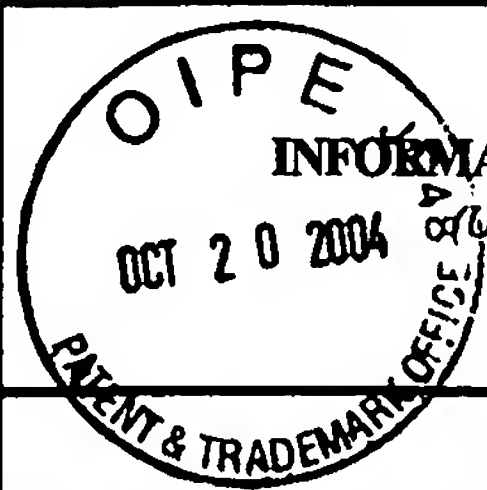
(Including Author, Title, Date, Pertinent Pages, Etc.)

		Prior Art - CHEMICAL PROCESSES IN GLASS POLISHING, Cook L.M., J. of Non-crystalline Solids, Vol. 120, pp 152-171.
		A CMP MODEL COMBINING DENSITY AND TIME DEPENDENCIES, Taber H. Smith, et al., 1999 CMP-MIC conference proceedings.

EXAMINER

DATE CONSIDERED

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP Section 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

**INFORMATION DISCLOSURE CITATION***(Use several sheets if necessary)*

Docket Number (Optional)

FIS92004-0210US1

Application Number

10/711,369

Applicant(s)

Venigalla, et al.

Filing Date

September 9, 2004

Group Art Unit

U.S. PATENT DOCUMENTS

*EXAMINER INITIAL	REF	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE

U.S. PATENT APPLICATION PUBLICATIONS

*EXAMINER INITIAL	REF	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE

FOREIGN PATENT DOCUMENTS

	REF	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
							YES	NO

OTHER DOCUMENTS*(Including Author, Title, Date, Pertinent Pages, Etc.)*

		CHEMICAL MECHANICAL PLANARIZATION OF MICROELECTRONIC MATERIALS, John Wiley and Sons, Inc., Wiley-Interscience publication, by Joseph M. Steigerwald, Shyam P. Murarka, Ronald J. Gutmann, year 1997, pages 140-147

EXAMINER**DATE CONSIDERED****EXAMINER:** Initial if citation considered, whether or not citation is in conformance with MPEP Section 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.